

## Description

The LY8AC15UL is a bi-directional TVS diode, utilizing leading monolithic silicon technology to provide fast response time and low ESD clamping voltage, making this device an ideal solution for protecting voltage sensitive high-speed data lines. It complies with IEC 61000-4-2 (ESD),  $\pm 20\text{kV}$  air and  $\pm 15\text{kV}$  contact discharge. It is assembled into an ultra-small lead-free DFN1006-2 package. The small size, ultra-low capacitance and high ESD surge protection make it an ideal choice to protect cell phone and high-power USB.

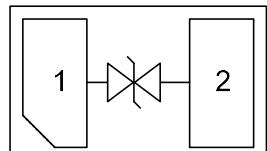
## Features

- Low clamping voltage
- Ultra low leakage current
- Operating voltage: 15V
- RoHS compliant
- IEC-61000-4-2 ESD  $\pm 20\text{kV}$  Air,  $\pm 15\text{kV}$  Contact
- Packaging: 7 inch reel, 10000pcs/reel

## Applications

- Cellular Handsets and Accessories
- USB Ports
- MDDI Ports
- Display Ports
- Digital Visual Interface (DVI)
- PCI Express and Serial SATA Ports

## Pin Configuration and Marking



Circuit and Pin Schematic

R15

## Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ )

Parameter	Symbol	Value
Peak Pulse Power (8/20μs)	$P_{PP}$	90W
Peak Pulse Current (8/20μs)	$I_{PP}$	2.5A
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	$V_{ESD}$	±20kV ±15kV
Ambient Temperature Range	$T_A$	-55°C to +125°C
Storage Temperature Range	$T_{STG}$	-55°C to +150°C

## Electrical Characteristics ( $T_A=25^\circ\text{C}$ )

Parameter	Symbol	Test Condition	Min.	Typ.	Max.
Reverse Working Voltage	$V_{RWM}$		-	-	15V
Breakdown Voltage	$V_{BR}$	$I_T = 1\text{mA}$	16.7V	-	-
Reverse Leakage Current	$I_R$	$V_{RWM} = 15\text{V}$	-	-	0.2μA
Clamping Voltage	$V_C$	$I_{PP} = 1\text{A}$ (8/20μs)	-	-	26V
		$I_{PP} = 2.5\text{A}$ (8/20μs)	-	-	35V
Junction Capacitance	$C_J$	$V_R = 0\text{V}$ , $f = 1\text{MHz}$	-	0.3pF	0.5pF

## Typical Characteristic Curves ( $T_A=25^\circ\text{C}$ )

Figure 1. Peak Pulse Power Rating Curve

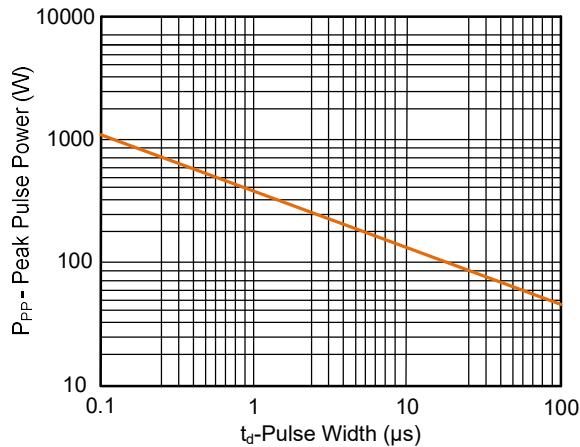


Figure 2. Pulse Derating Curve

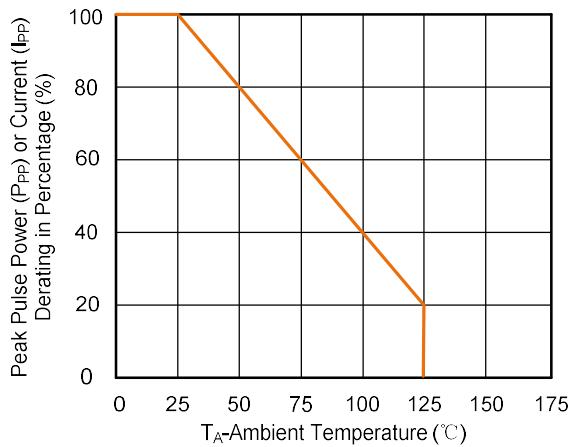


Figure 3. Clamping Voltage vs. Peak Pulse Current

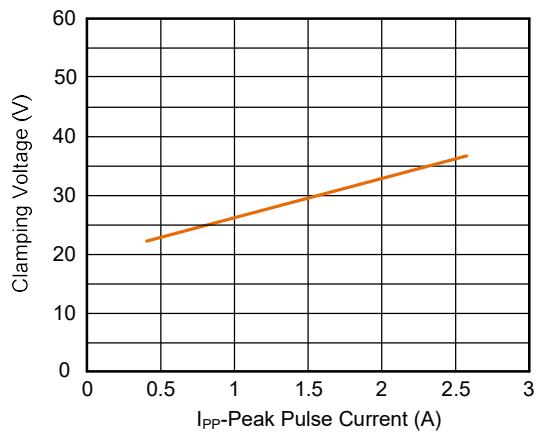


Figure 4. Junction Capacitance vs. Reverse Voltage

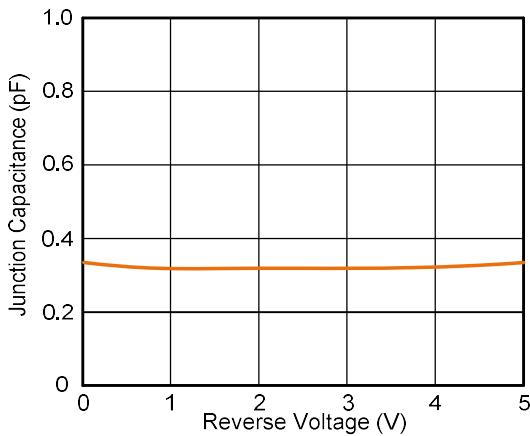


Figure 5. Pulse Waveform (8/20μs)

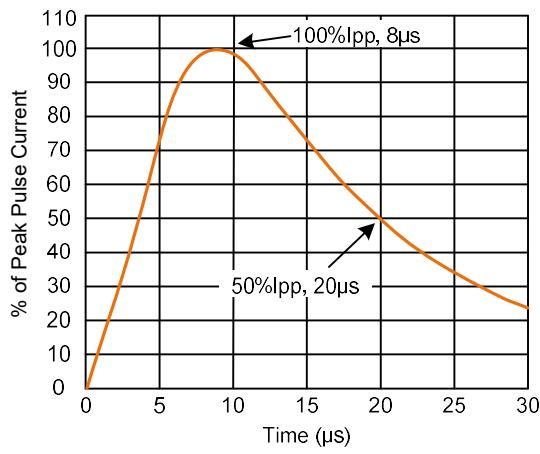
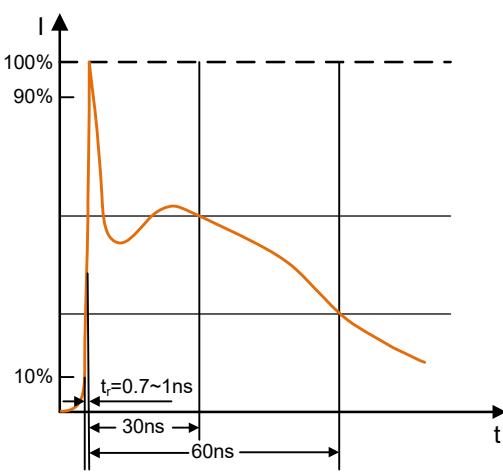
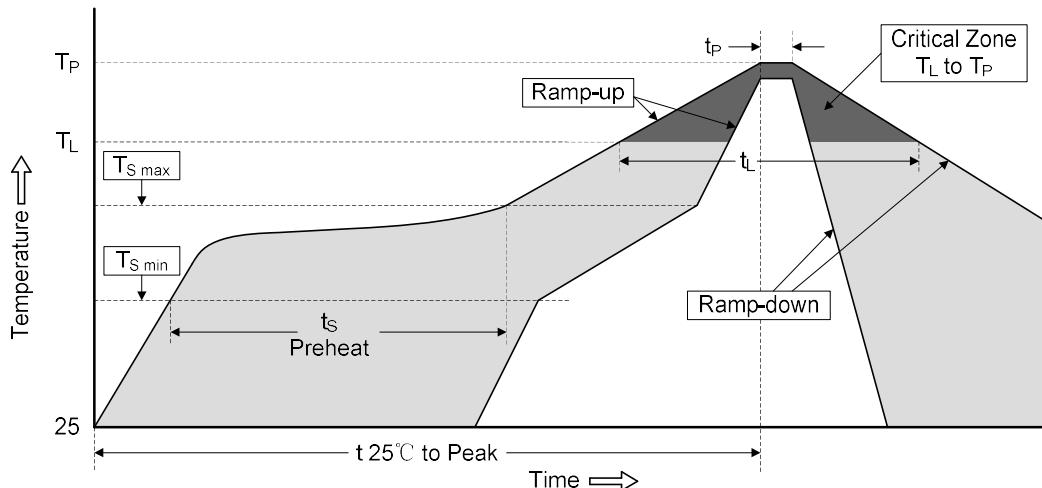


Figure 6. Pulse Waveform (IEC61000-4-2)



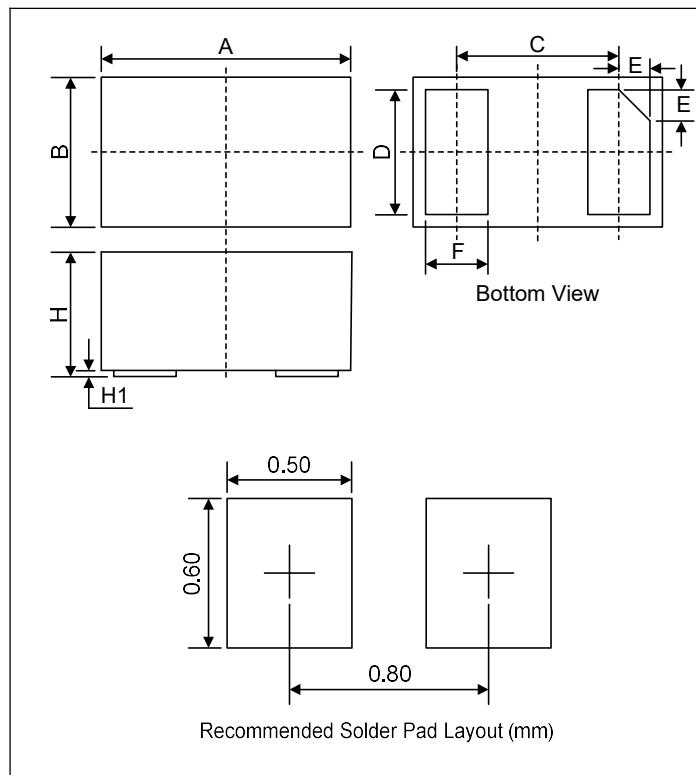
## Soldering Parameters

### Reflow Soldering



Profile Feature	Pb-Free Assembly
Average ramp-up rate ( $T_L$ to $T_P$ )	3°C/second max.
Preheat	
-Temperature Min ( $T_{S\ min}$ )	150°C
-Temperature Max ( $T_{S\ max}$ )	200°C
-Time (min to max) ( $t_s$ )	60-180 seconds
$T_{S\ max}$ to $T_L$	
-Ramp-up Rate	3°C/second max.
Time maintained above:	
-Temperature ( $T_L$ )	217°C
-Time ( $t_L$ )	60-150 seconds
Peak Temperature ( $T_P$ )	260°C
Time within 5°C of actual Peak Temperature ( $t_P$ )	20-40 seconds
Ramp-down Rate	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.

## Dimensions (DFN1006-2)



Symbol	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	0.95	1.05	0.037	0.041
B	0.55	0.65	0.022	0.026
C	0.65BSC		0.026BSC	
D	0.45	0.55	0.018	0.022
E	0.07	0.17	0.003	0.007
F	0.20	0.30	0.008	0.012
H	0.45	0.55	0.018	0.022
H1	0.00	0.05	0.000	0.002